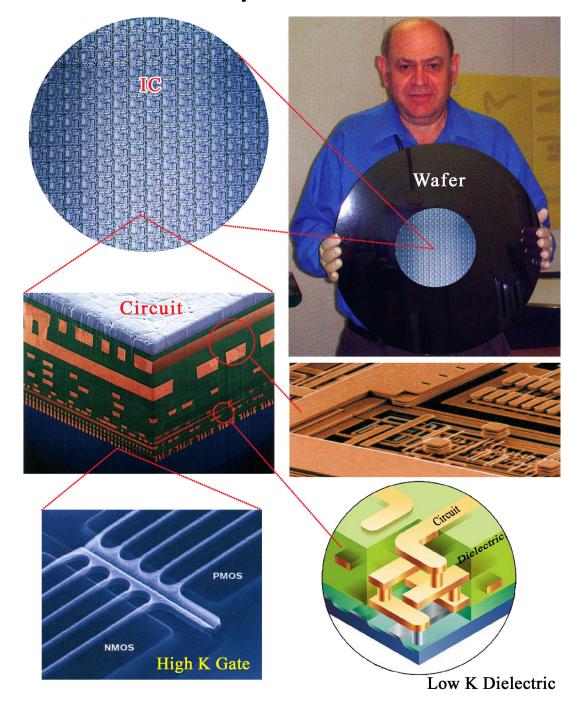
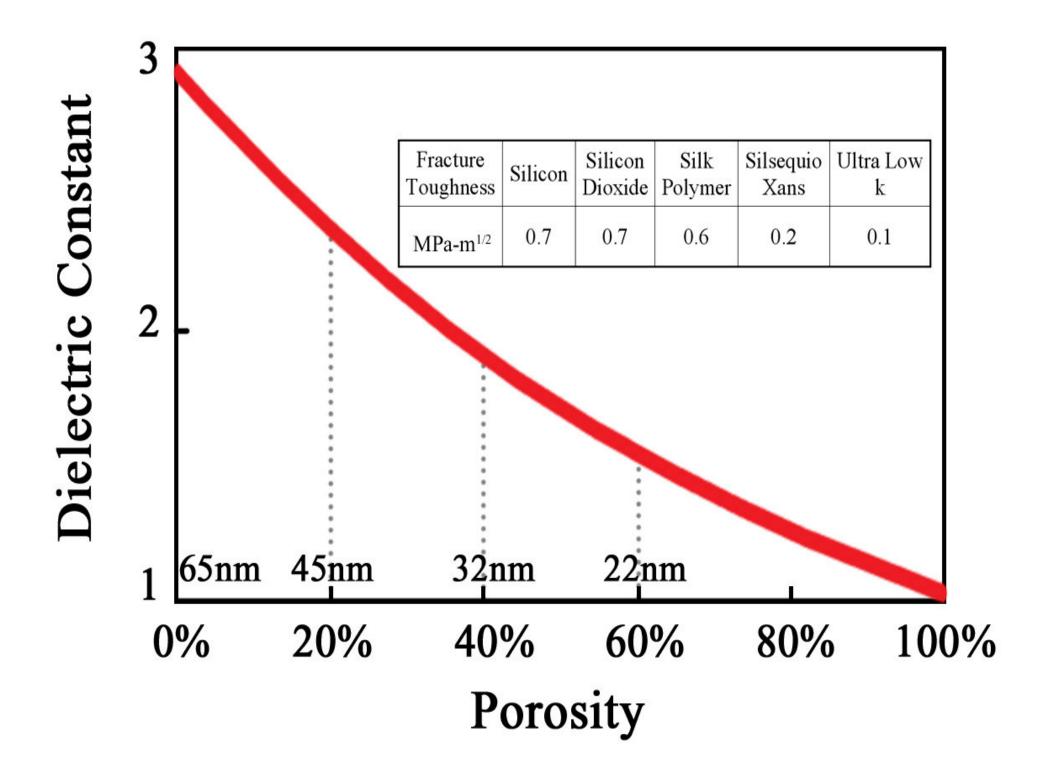
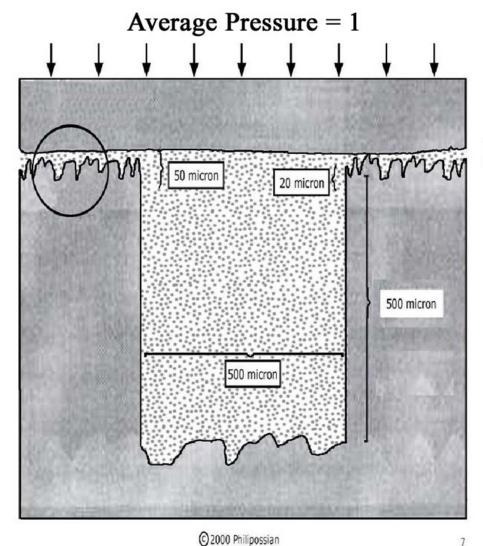
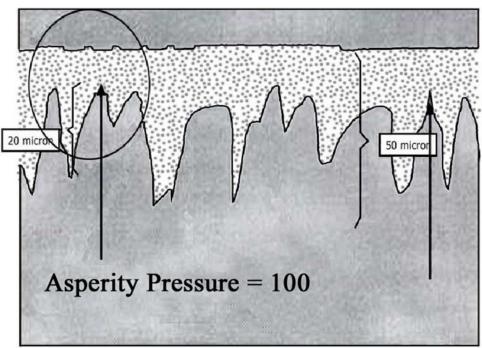


Moore's Law For 2012 & Beyond : 450 mm Wafer/ 22 nm Node $\geq 10^7$

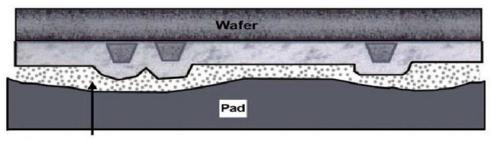




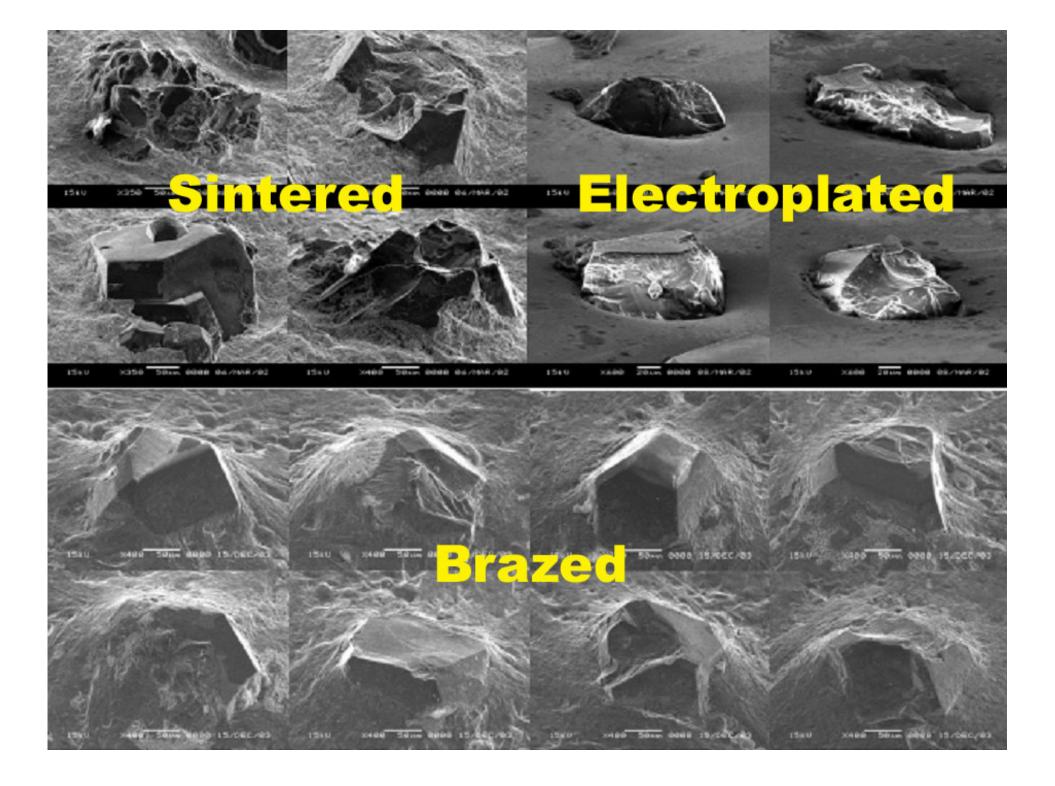


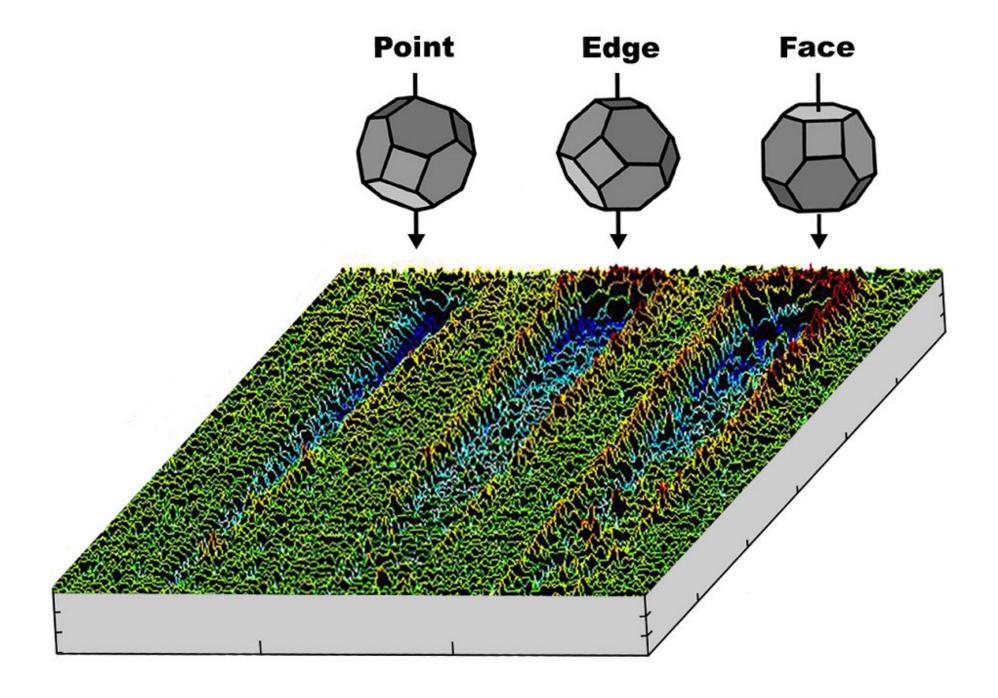


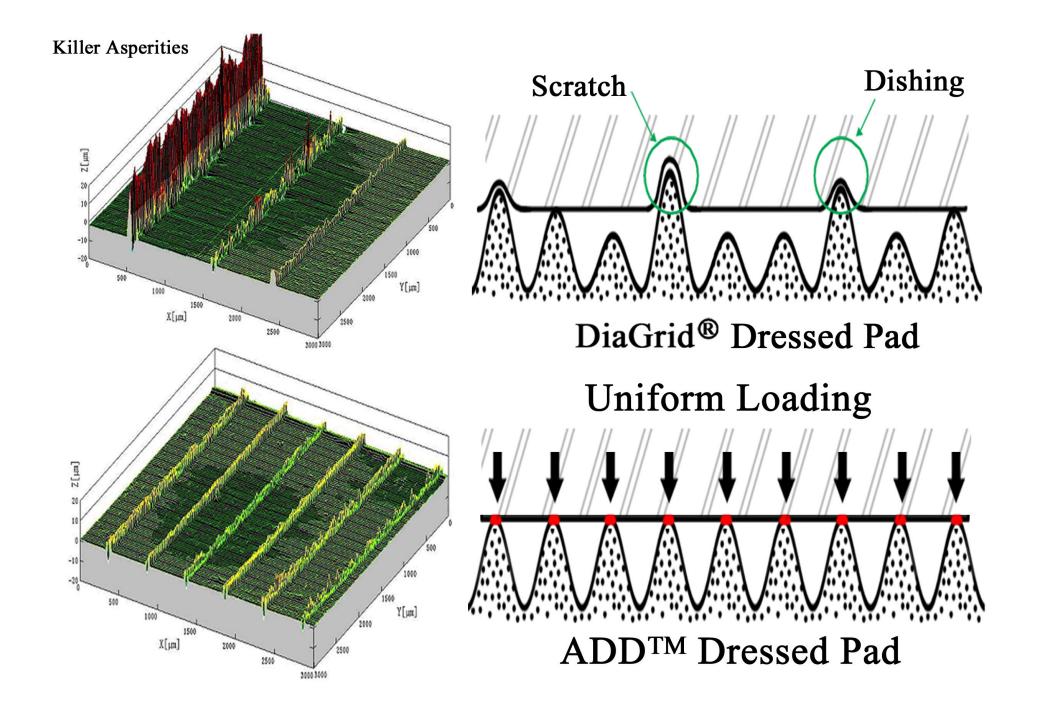
© 2000 Philipossian



Abrasive Pressure = 1000



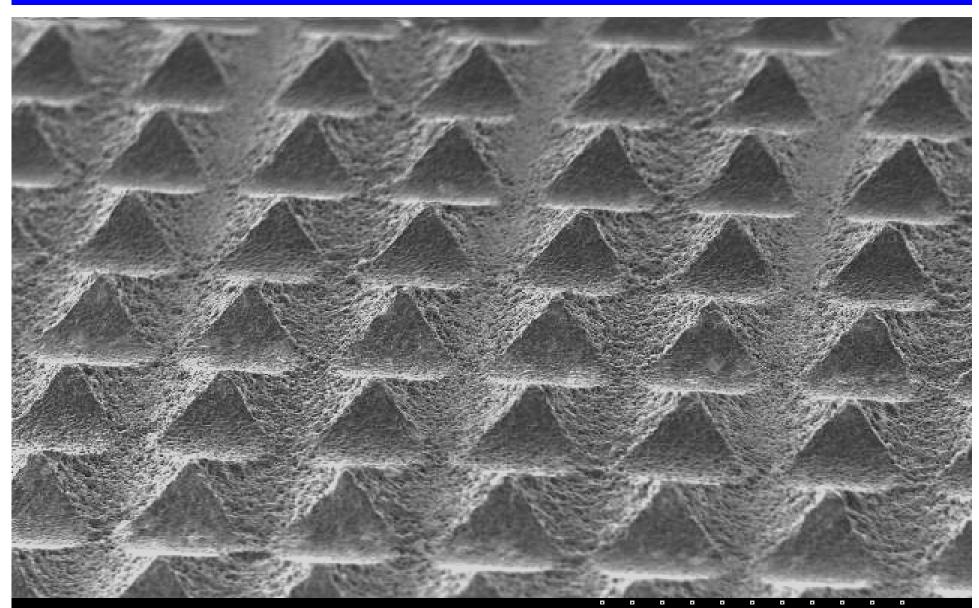




DiaGrid Disks & Advanced Diamond Disks (ADD)



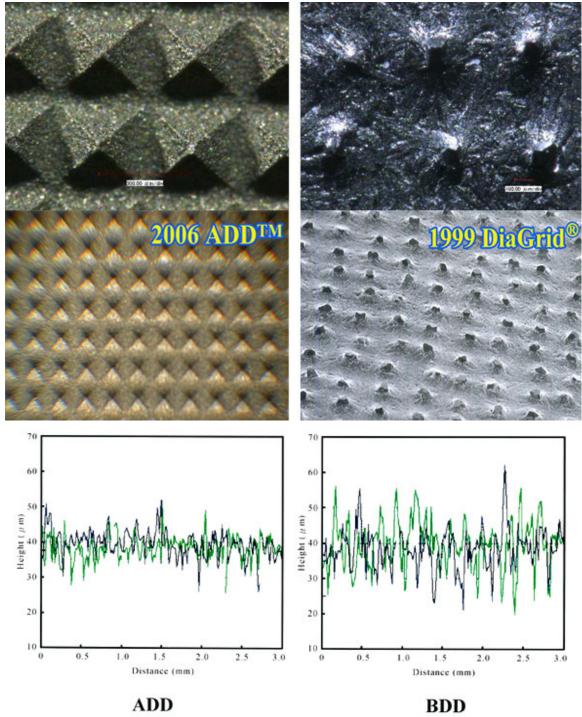
Poly Crystalline Diamond

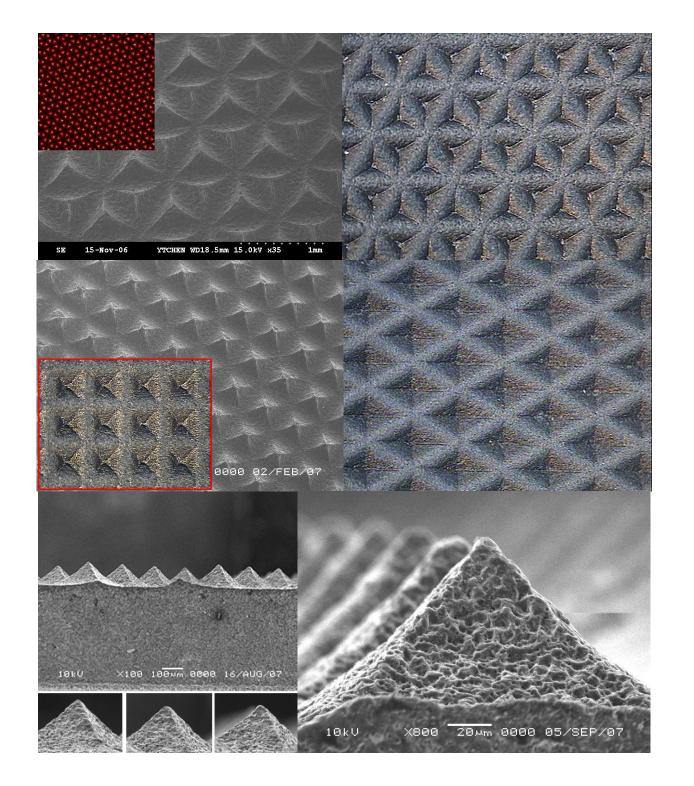


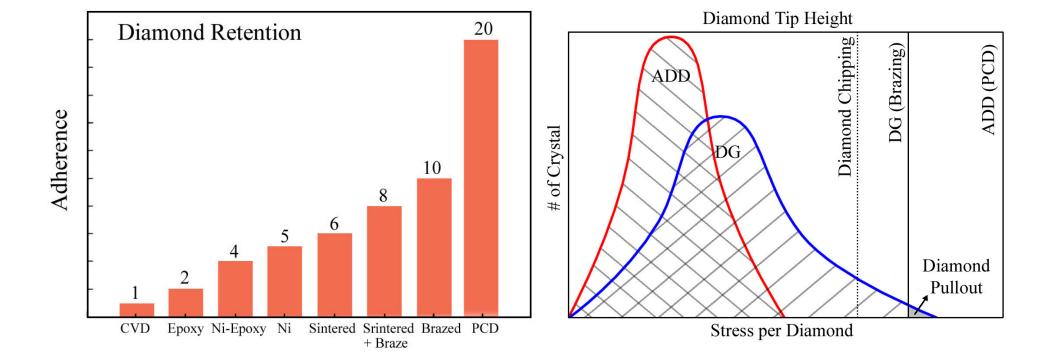
12-Sep-06

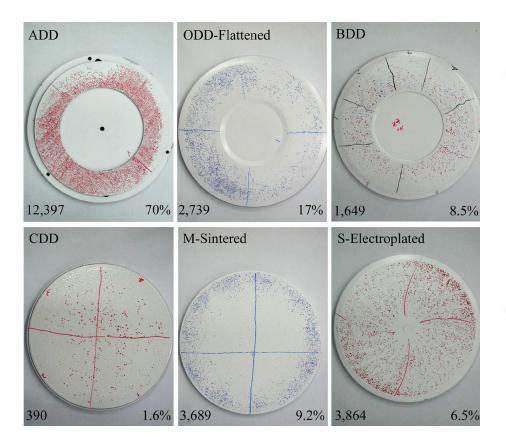
YTCHEN WD18.3mm 15.0kV x40

1mm

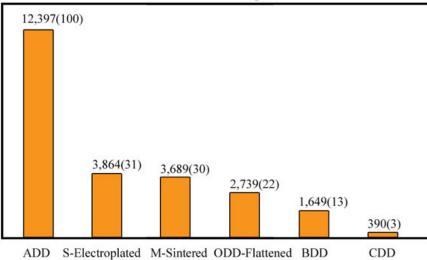






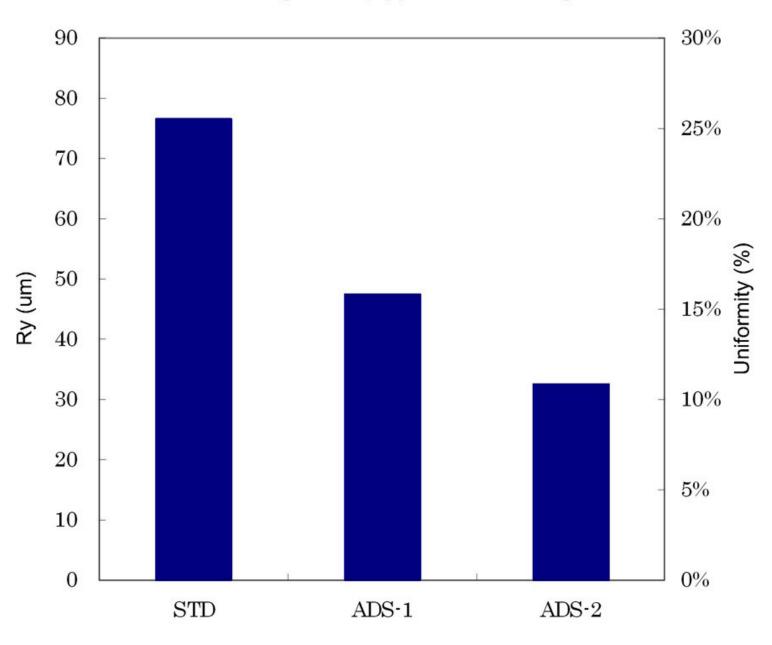


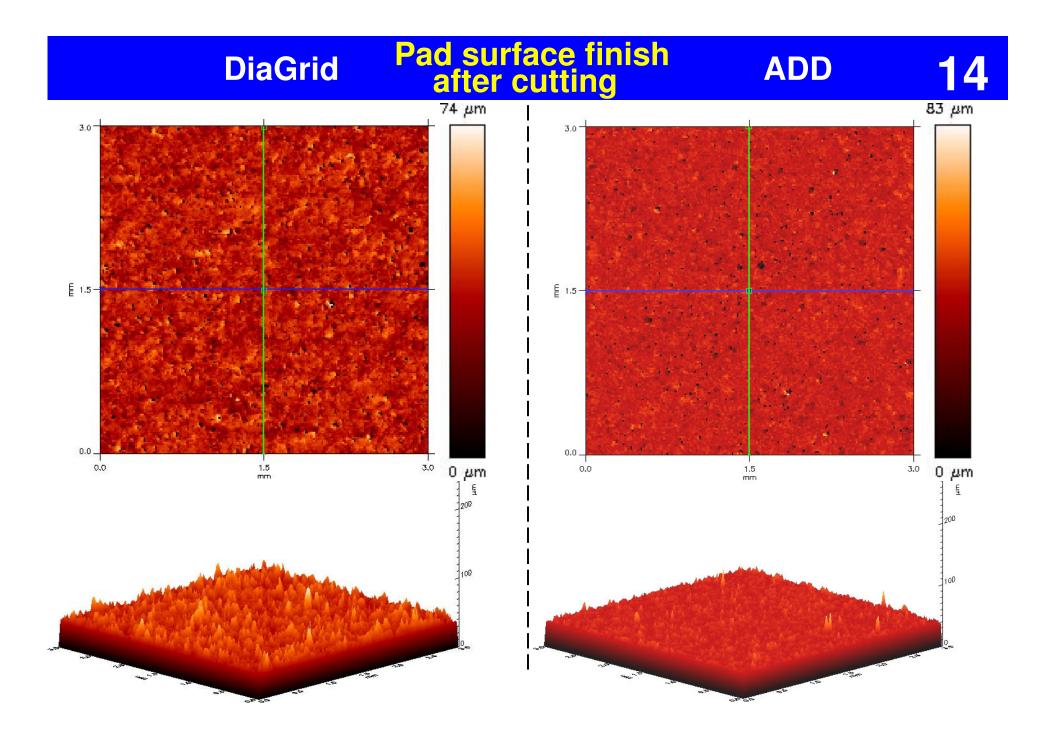
Number of Working Diamond

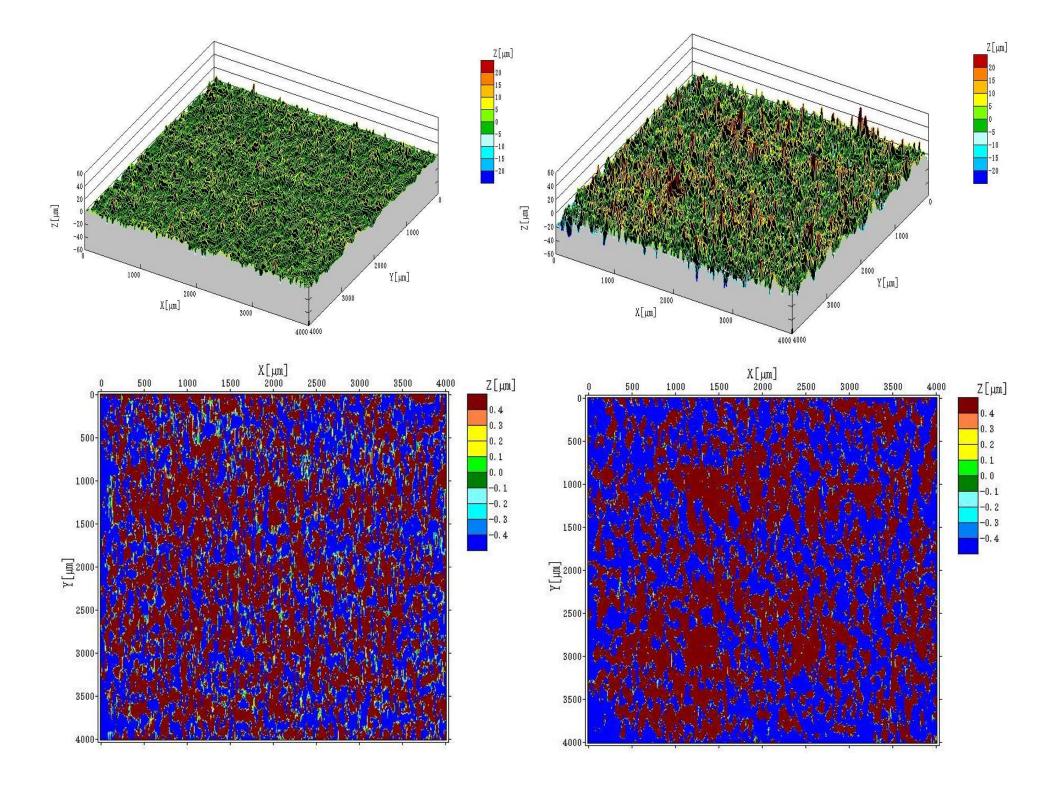


Pad Roughness (60min Conditioning)

Pad Roughness (Ry) after Polishing







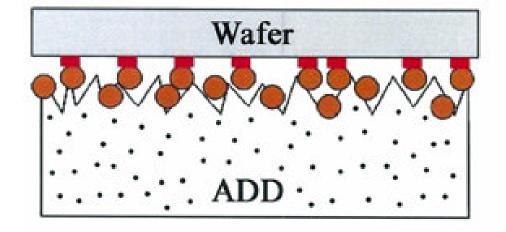
Slurry on Pad Contact Angle

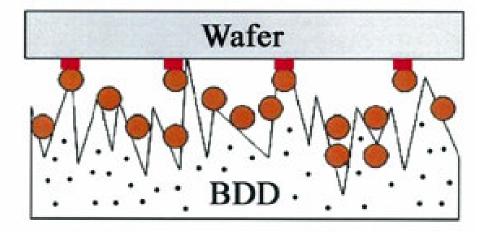


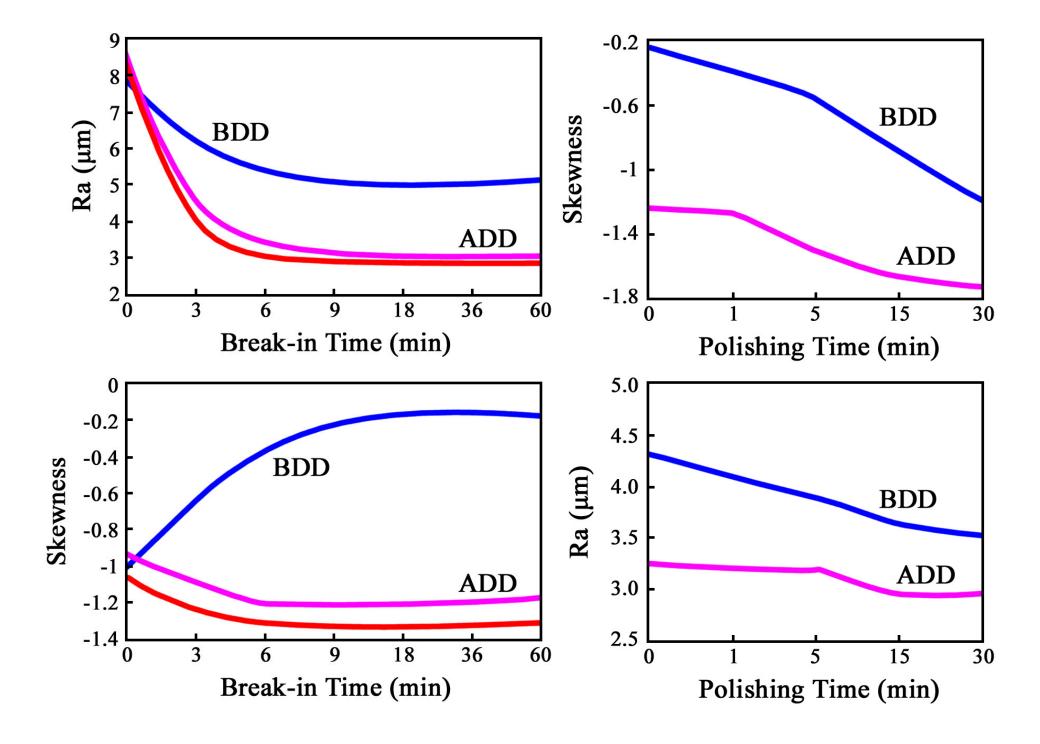
= 65-70 degree

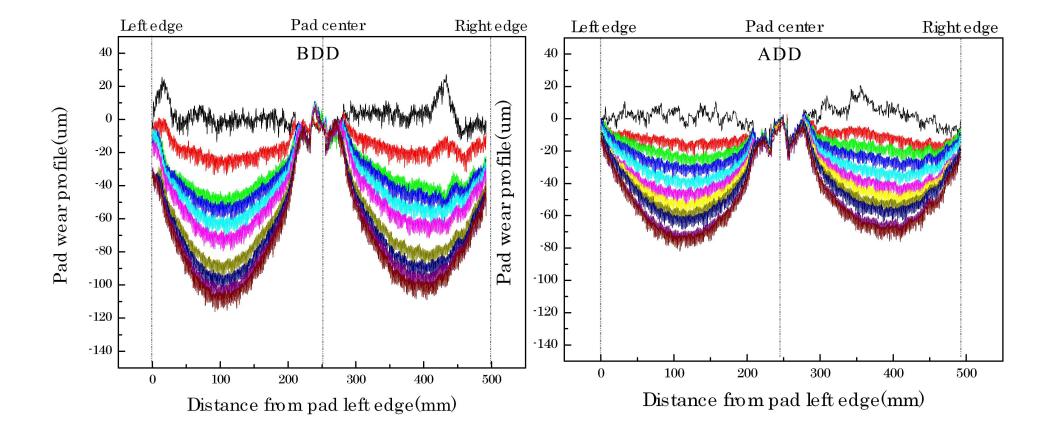


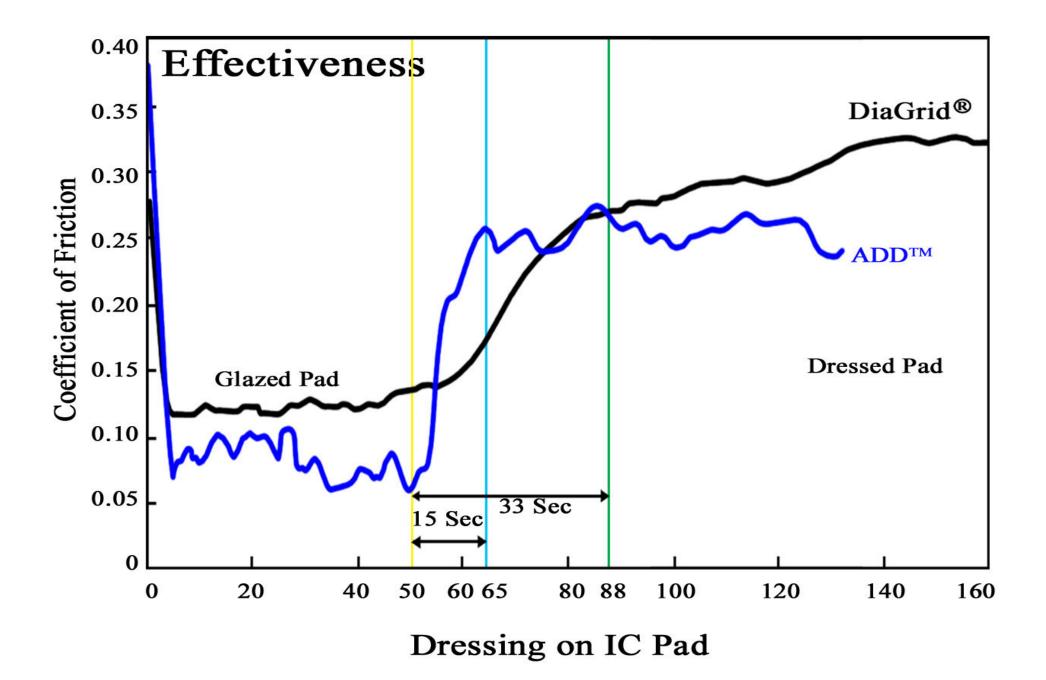
= 90-95 degree

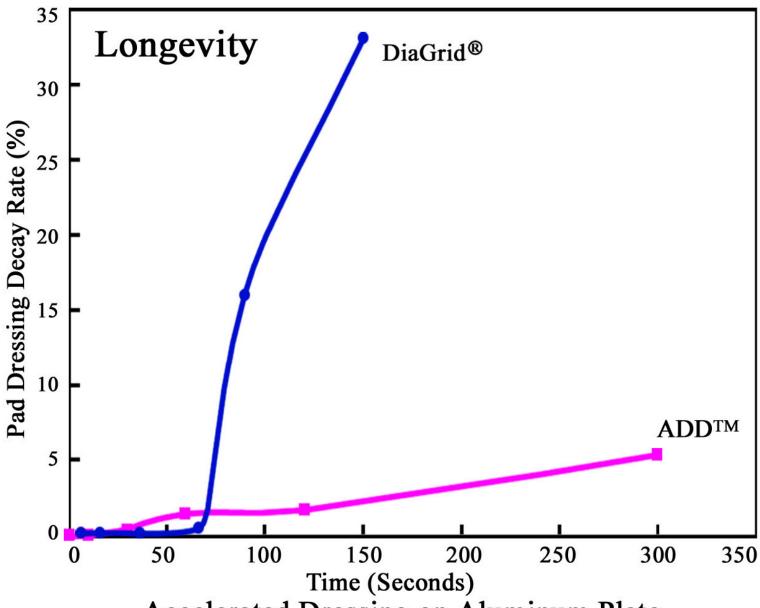




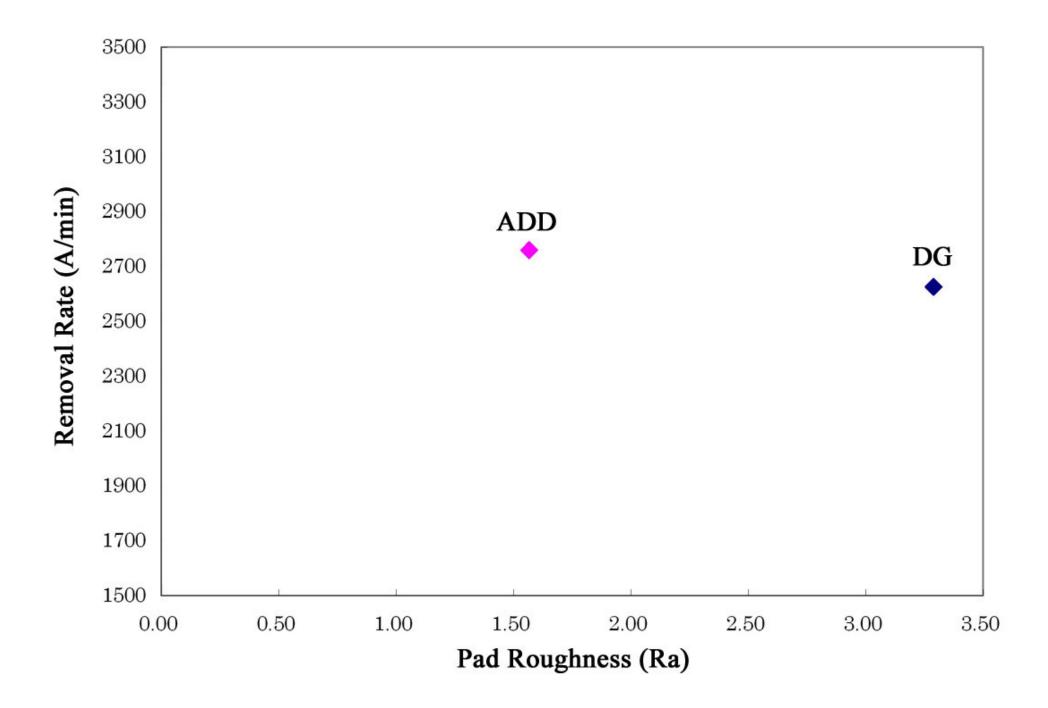


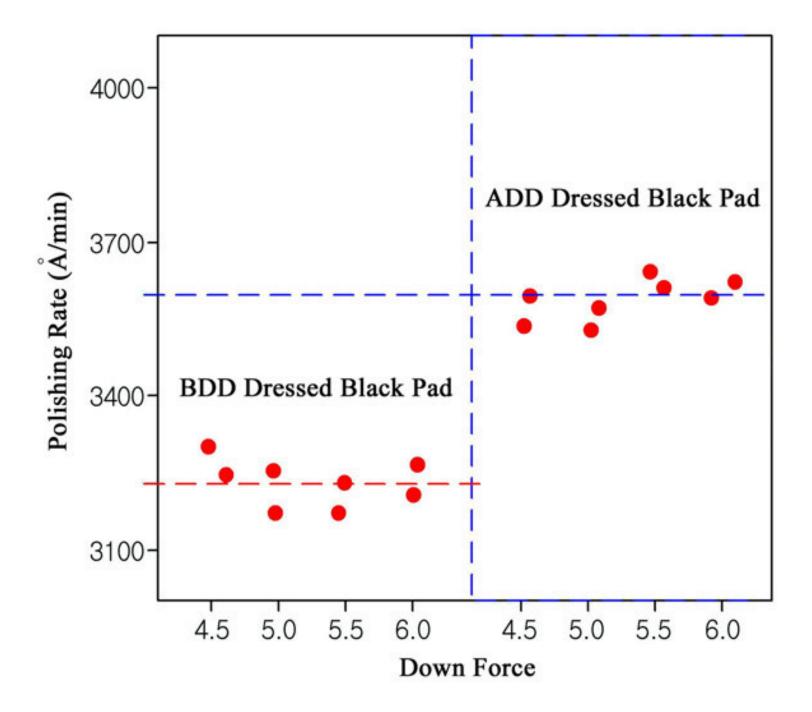


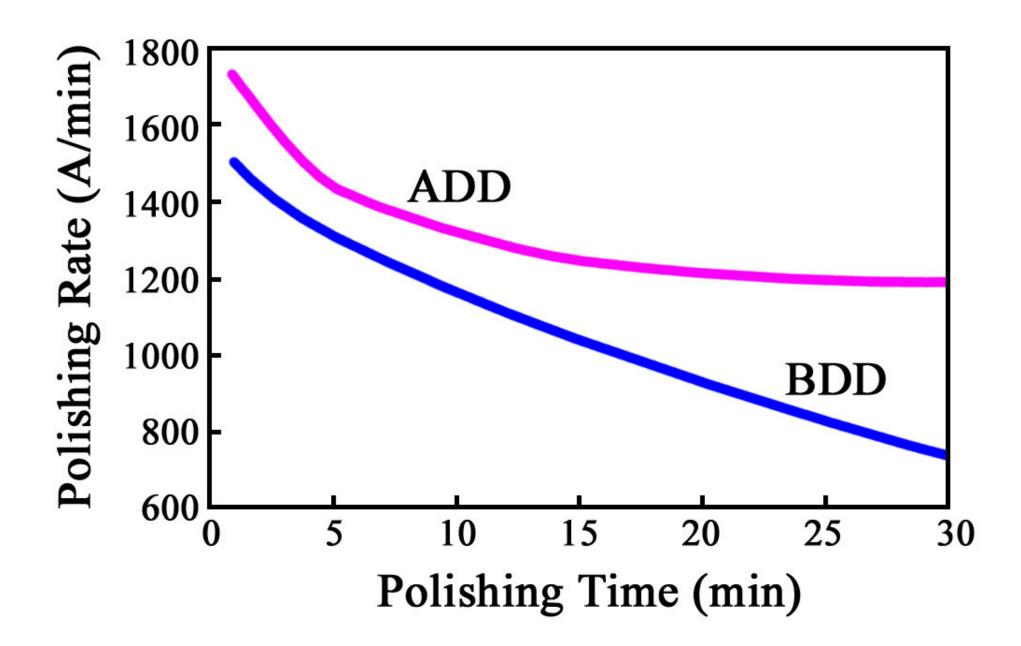


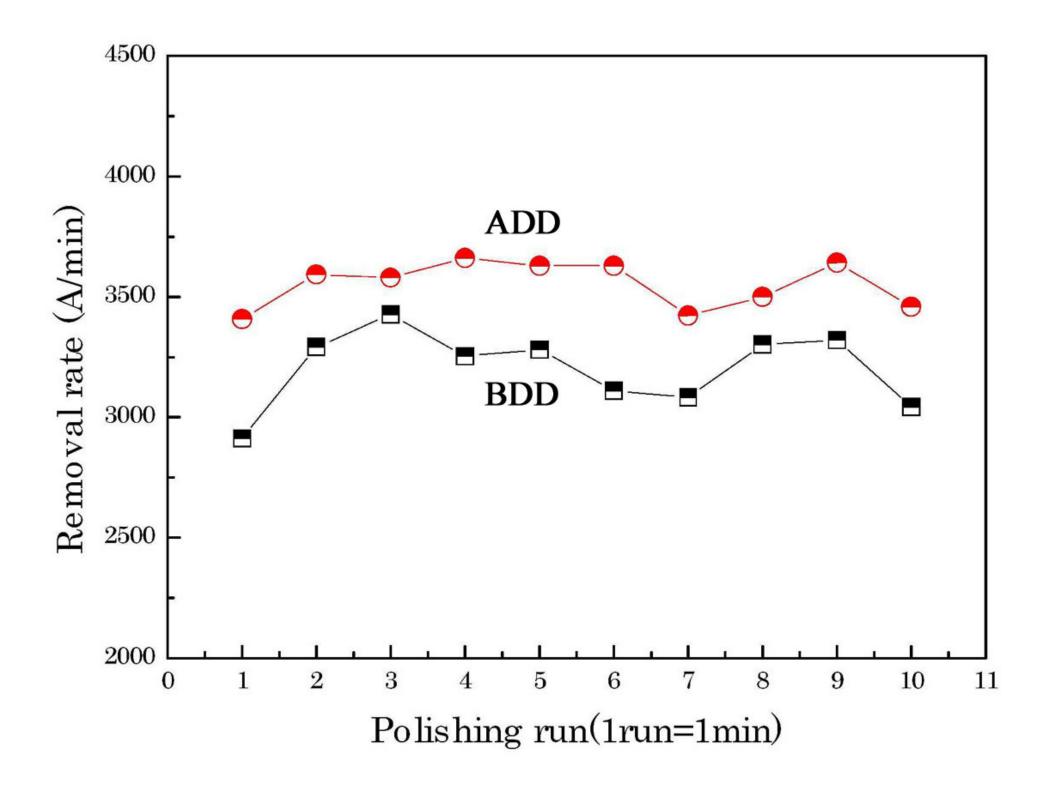


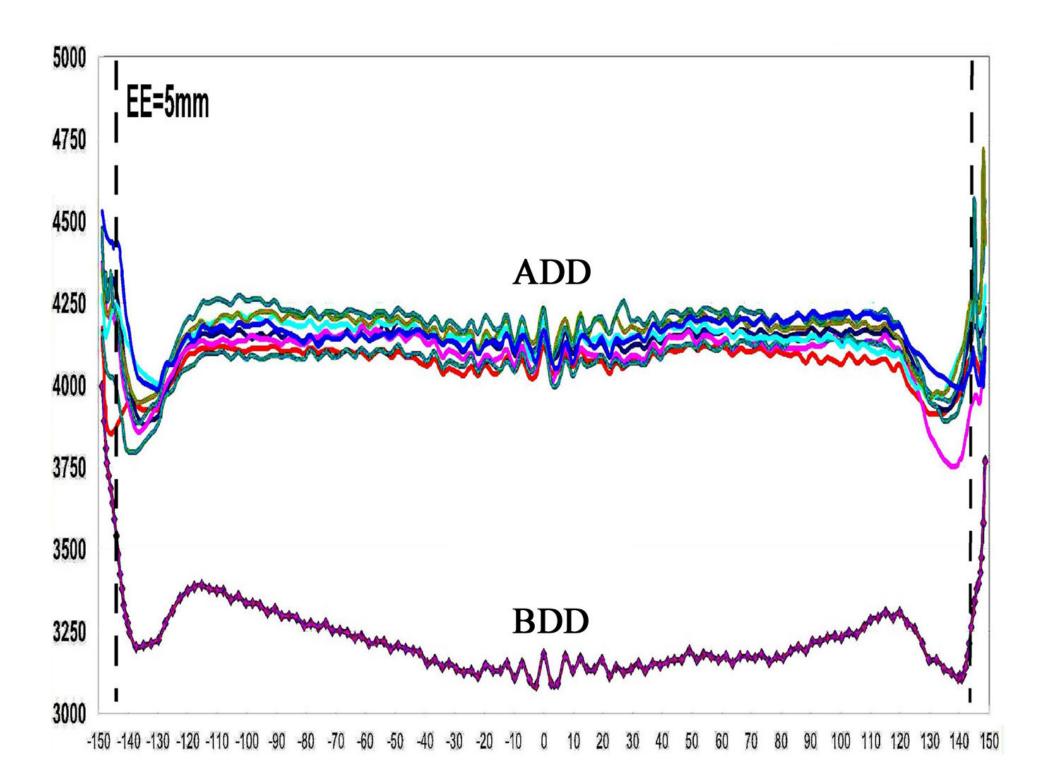
Accelerated Dressing on Aluminum Plate

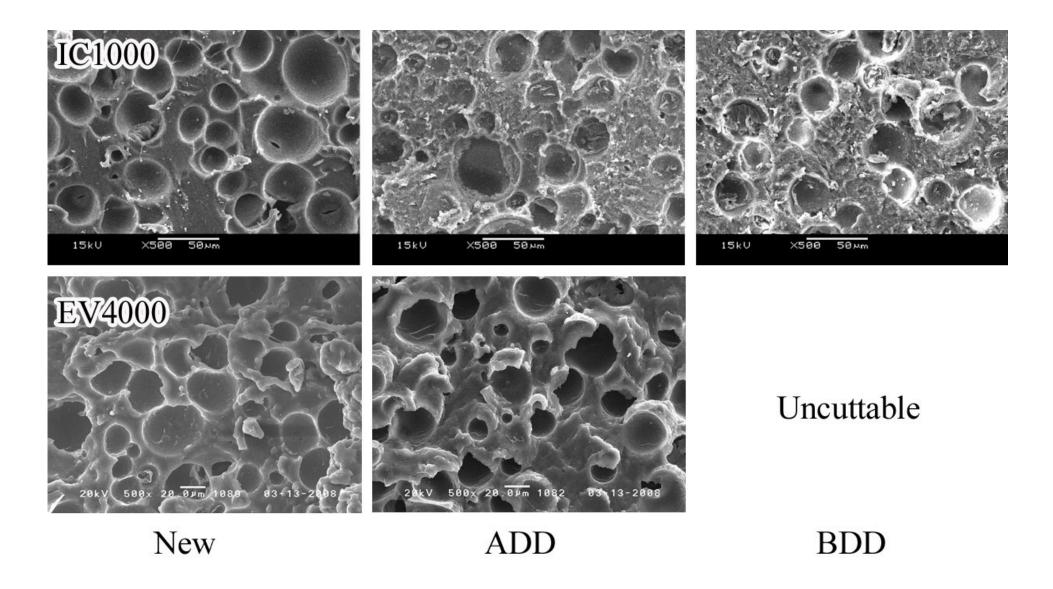


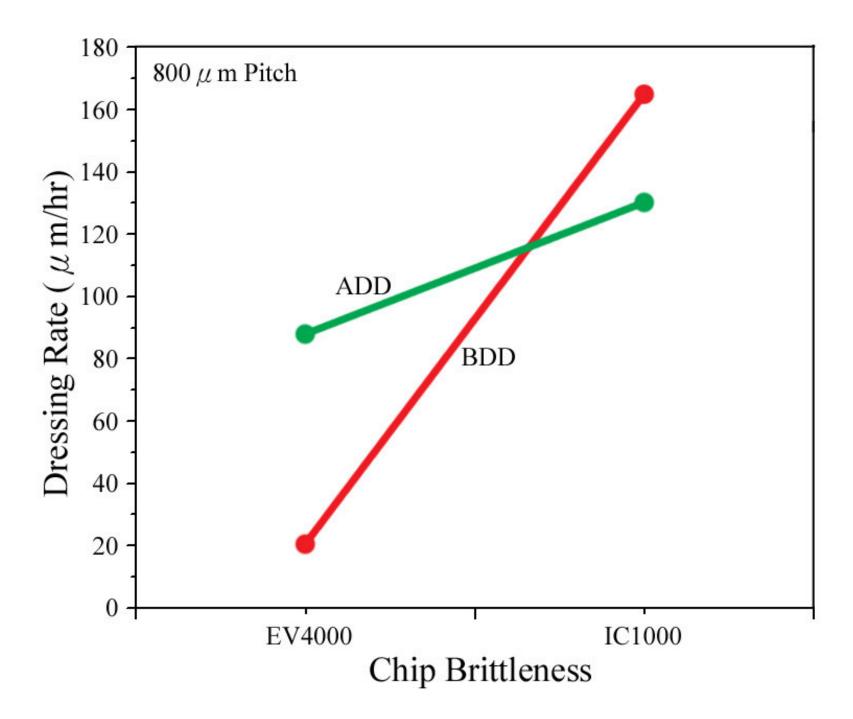












The Organic Diamond Disk (ODD) for Chemical Mechanical Planarization

Dr. James Sung CMPUG Meeting=April 9, 2008

